

2.2 Non-Government publications. The following document forms a part of this document to the extent specified herein. Unless otherwise specified, the issues of the documents which are DoD adopted are those listed in the issue of the DoDISS cited in the solicitation. Unless otherwise specified, the issues of documents not listed in the DoDISS are the issues of the documents cited in the solicitation (see 6.2).

ASTM-B16/B16M ROD, BRASS, FREE-CUTTING, BAR AND SHAPES FOR USE IN SCREW MACHINES.
(AMERICAN SOCIETY for TESTING and MATERIALS, 1100 Barr Harbor Drive, West Conshohocken PA 19428-2959).

2.3 Order of Precedence. In the event of a conflict between the text of this document and the references cited herein, the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 General. The individual item requirements shall be in accordance with MIL-PRF-19500, and as specified herein.

3.2 Abbreviations, symbols, and definitions. Abbreviations, symbols, and definitions used herein shall be as specified in MIL-PRF-19500. and as follows:

1/G Reciprocal of conductance (IF impedance).

SWR Standing wave ratio.

3.3 Interface and physical dimensions. The semiconductor diode shall be of symmetrical construction and shall consist of a cylindrical body having pins on both ends. The body outline with removable base adapter shall conform to figure 1. Organic package sealants may be used at the option of the manufacturer.

3.3.1 Base adapter. The base adapter shall be of the design, construction and physical dimensions shown on figure 2.

3.3.2 Plating. The diode and base adapter shall be plated as specified on figures 1 and 2.

3.4 Performance characteristics. Performance characteristics shall be in accordance with tables I, and II.

3.5 Marking. The marking shall be placed on each device in accordance with MIL-PRF-19500, except that the manufacturer's identification and country of origin may be omitted.

3.5.1 Matched diodes. The "M" suffix for matched diodes shall be omitted in the type designation on each device. Diodes meeting the matching requirements of this drawing will be packaged with a statement to that effect (see 4.4.2 and 4.4.3).

3.6 Burnout by multiple pulses. At the end of all manufacturing processes and prior to selecting samples for testing, all diodes shall be capable of meeting burnout by a series of RF pulses with the test conditions as follows:

P = 20 watts	$t_p = 6 \pm 3$ nanoseconds
f = 8.8 to 9.8 GHz	$R_L = 100 \Omega$
Exposure = 15,000 pulses minimum	Holder: see below

Test data demonstrating that the holder used meets this requirement shall be made available to the government representative upon request (see figures 3 and 4).

3.7 Manufacturer eligibility. To be eligible to supply devices to this drawing, the manufacturer shall perform conformance inspection in accordance with procuring activity's requested first article testing requirements in accordance with 4.3 herein. Devices specified herein shall meet traceability and lot formation requirements of MIL-PRF-19500 except as modified by the procuring activity.

3.8 Submission of certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as a source of supply in 6.5. The certificate of compliance submitted to DSCC-VAC, prior to listing as a source of supply in 6.5, shall state that the manufacturer's product meets the applicable requirements of MIL-PRF-19500 and the requirements herein.

3.9 Certificate of conformance. A certificate of conformance shall be provided with each lot of devices delivered in accordance with this drawing.

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3.10 Recycled, recovered, or environmentally preferable materials. Recycled, recovered, or environmentally preferable materials should be used to the maximum extent possible provided that the material meets or exceeds the operational and maintenance requirements, and promotes economically advantageous life cycle costs.

3.11 Workmanship. The semiconductor shall be uniform in quality and free from any defects that will affect life, serviceability, or appearance.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection shall be in accordance with MIL-PRF-19500, and as specified herein.

4.1.1 Structurally similar device types. Types 1N23WE and 1N23WG are structurally similar devices. Any type may be sampled for groups B and C inspections to accept all for quality conformance inspection.

4.2 Test conditions. Unless otherwise specified herein, the test conditions, when applicable, shall be as follows:

- P = 1.0 mW ± 5 percent
- N_{if} ≥ 1.5 dB
- R_L = 100 ± 1Ω
- f = 9375 ± 5 MHz
- Z_m = 400 ± 10Ω
- Holder - Drawing C65019 or equivalent

4.2.1 Holder. The diode holder DSCC Drawing C65019, or equivalent, shall be used for all electrical test measurements.

4.3 Conformance inspection. Conformance inspection shall consist of the examinations and tests specified in groups A and B.

4.3.1 Group A inspection. Group A inspection shall consist of the inspections and tests specified in table I.

4.3.2 Group B inspection. Group B inspection shall consist of the inspections and tests specified in table II.

4.4 Methods of examination and test. Methods of examination and test shall be as specified in the appropriate tables and as follows:

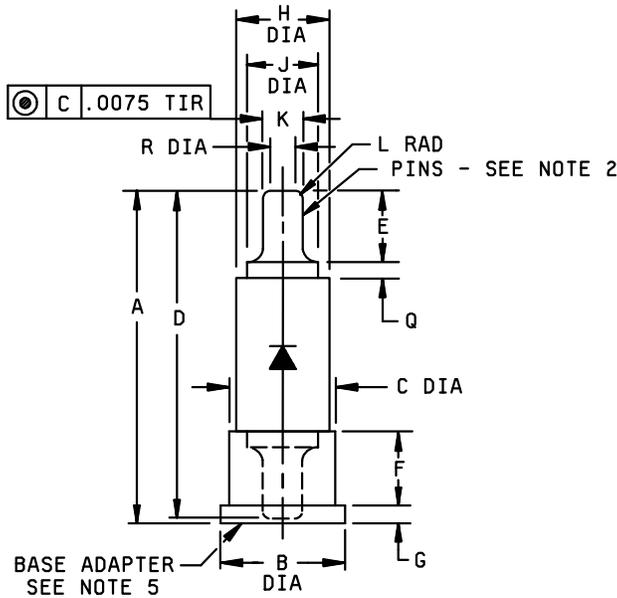
4.4.1 High-temperature operation. The semiconductor diode shall be placed in the mixer holder. The ambient temperature of the diode, with test conditions specified for the overall noise figure, shall be raised to +150°C and maintained at this temperature until equilibrium is reached. The F_{om} shall then be determined and shall be less than the specified limit. The temperature shall then be returned to 25 ± 3°C at which time F_{om} shall be less than the specified limit.

4.4.2 Matched pair "M" suffix (forward polarity). The matched pair (M suffix) shall consist of two diodes, tested to requirements of subgroup 3, table I, having the anode connected to the adapter.

4.4.3 Matched pair "MR" suffix (forward and reverse polarity). The matched forward and reverse pair (MR suffix) shall consist of two diodes, tested to requirements of subgroup 3, table I: one diode having the anode connected to the adapter (forward polarity) and the second diode having the cathode connected to the adapter (reverse polarity).

4.4.4 Time limit for endpoints. End point tests for qualification and quality conformance inspection shall be completed within 96 hours after completion of the last test in the subgroup.

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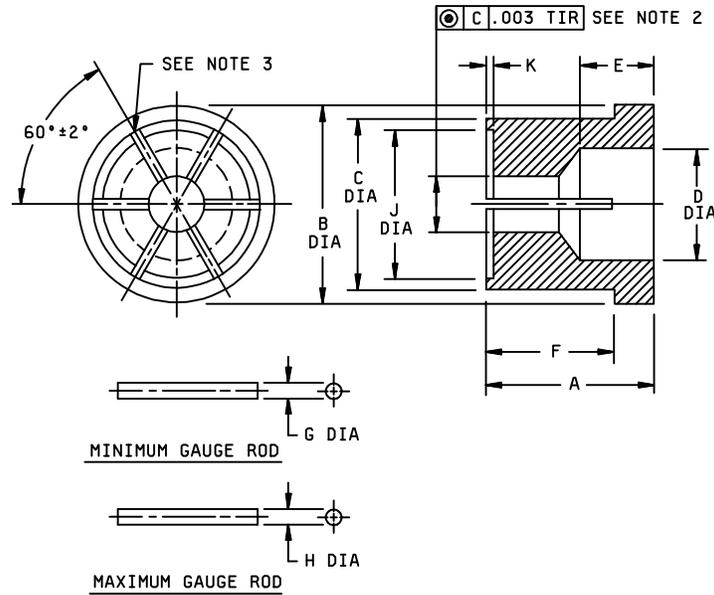
Ltr	Dimensions				Notes
	Inches		Millimeters		
	Min	Max	Min	Max	
A	.800	.840	20.32	21.34	
B	.292	.296	7.42	7.52	
C	.246	.250	6.25	6.35	
D	.766	.792	19.46	20.12	
E	.180	.190	4.57	4.83	6
F	.195	.199	4.95	5.05	
G	.047	.057	1.19	1.45	
H	.222	.240	5.64	6.10	
J	.195	.215	4.90	5.46	5
K	.092	.094	2.34	2.39	2, 5, 7
L	.030	.046	.76	1.17	5
Q	.020	.030	.51	.76	5
R		.030		.76	5

NOTES:

1. Metric equivalents are given for general information only.
2. The ends of both pins shall be smooth with no burrs or sharp edges. Within the diameter R, a recess is allowed on both ends of the pins.
3. Metal parts shall be plated 10 msi minimum.
4. The polarity shall be indicated by an arrow, with the arrow pointing in the direction of easier current flow.
5. Applies to both pins.
6. Removable base adapter shall establish the forward or reverse polarity.
7. Eccentricity between both pins and the base dimension 'C' should not exceed 0.0075 inches.
8. Metal parts shall be gold plated 10 msi minimum.

FIGURE 1. Semiconductor device, diode types 1N23WE, 1N23WEM, 1N23WEMR, 1N23WG, 1N23WGM and 1N23WGMR.

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Ltr	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	.242	.256	6.15	6.50
B	.292	.296	7.42	7.52
C	.246	.250	6.25	6.35
D		.187		4.75
E		.100		2.54
F	.195	.199	4.95	5.05
G	.0915	.0920	2.32	2.34
H	.0940	.0945	2.39	2.40
J	.216	.221	5.49	5.61
K	.031	.036	.79	.91

NOTES:

1. Metric equivalents (to nearest .01 mm) are given for general information only.
2. This diameter should be .100 (2.54 mm) max diameter before closing jaws. This diameter shall then be sufficiently closed and the adapter so tempered that it will fit on the minimum gage rod and maximum gage rod, in each case with a snug fit (for hand assembly).
3. Each slot shall be .013 (.330 mm) min, .017 (.132 mm) max wide by .185 (4.70 mm) deep before closing. The six slots are equally spaced.
4. The material for the adapter shall be brass in accordance with ASTM-B16/B16M, or equivalent.
5. Metal parts shall be gold plated 10 msi minimum.
6. All burrs and sharp edges shall be removed.

FIGURE 2. Removable base adapter, included as a part of types 1N23WE, 1N23WEM, 1N23WEMR, 1N23WG, 1N23WGM and 1N23WGMR.

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TABLE I. Group A inspection.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 1</u>						
Visual and mechanical examination	2071					
<u>Subgroup 2</u>						
Voltage standing wave ratio (see 4.2)	4136	I = 1.0 mAdc	VSWR		1.3	ratio
Intermediate frequency conductance (see 4.2)	4116	f = 60 - 2000 Hz	1/G	335	465	ohms
Overall noise figure (see 4.4.1)	4126	Test condition A	F _{om}			
1N23WE					7.5	dB
1N23WG					6.5	dB
<u>Subgroup 3</u>						
Matched pair requirements (see 4.4.2 and 4.4.3)						
Conversion loss unbalance	4101		ΔL		0.3	dB
Intermediate frequency conductance unbalance	4116		Δ1/G		25	ohms

TABLE II. Group B inspection.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
<u>Subgroup 1</u>						
Physical dimensions	2066	See figures 1 and 2				
<u>Subgroup 2</u>						
Thermal shock (temperature cycling)	1051	Test condition F; T _(high) = +150°C +5°C, -0°C				
Terminal strength:						
Tension	2036	Test condition A; 1 lb; t = 30 sec				
Torque	2036	Test condition D ₁ ; t = 30 sec				

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TABLE II. Group B inspection - continued.

Inspection <u>1/</u>	MIL-STD-750		Symbol	Limits		Unit
	Method	Conditions		Min	Max	
Moisture resistance	1021	Omit initial conditioning	Fom			
End points: Overall (average) noise figure (see 4.4.1)	4126	Test condition A				
1N23WE 1N23WG					8.5 7.5	dB dB
<u>Subgroup 3</u>						
Shock	2016	500 G; t \cong 1 ms 5 blows in each orientation: X ₁ , Y ₁ , and Y ₂				
Vibration, variable frequency	2056	15 G; 50 to 2,000 cps				
End points: (same as for group A subgroup 2)						
<u>Subgroup 4</u>						
High temperature operation (see 4.5.1)		T _A = 150°C Test condition A	Fom			
Overall (average) noise figure						
1N23WE 1N23WG				10.5 9.5	dB dB	
Overall (average) noise figure		Test condition A T _A = 25° C	Fom			
1N23WE 1N23WG					8.5 7.5	dB dB
<u>Subgroup 5</u>						
High temperature life (nonoperating)	1031	T _A = 150°C				
End points: (Same as subgroup 2)						

1/ For sample size, see MIL-PRF-19500.

2/ Shall only be capable of passing this test.

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NOTES:

1. The holder used with a diode mounted in it and terminated with 100 ohms and with an incident power of 1.0 mW to the holder shall have a 2.0 maximum VSWR over a minimum band width of 1/(pulse width used) on both sides of the RF burnout test frequency used.
2. A suitable circuit for generating nanosecond pulses of the required power is described in the 1969 IEEE-G-MTT International Microwave Symposium Conference Record. (See figure 4).

FIGURE 3. Multiple RF pulse burnout circuit.

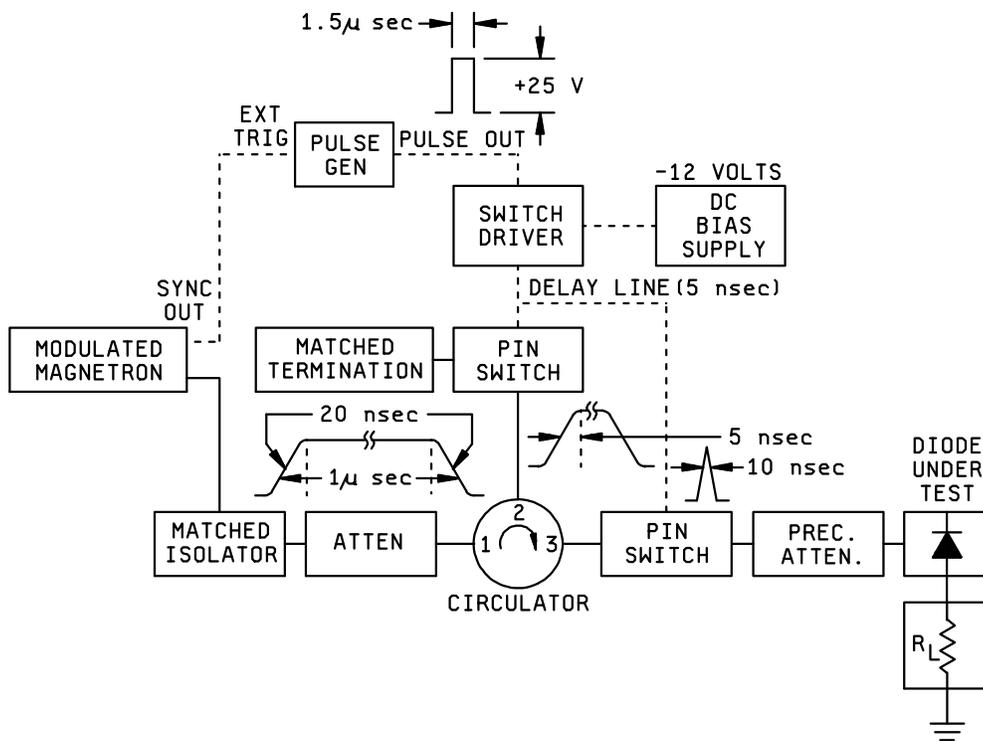


Figure 4 RF pulse burnout system.

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4.4.5 Time limit for end points. End point tests for qualification and quality conformance inspection shall be completed within 96 hours after completion off the last test in the subgroup.

5. PACKAGING

5.1 Packaging. For acquisition purposes, the packaging requirements shall be as specified in the contract or order (see 6.2). When actual packaging of materiel is to be performed by DoD personnel, these personnel need to contact the responsible packaging activity to ascertain requisite packaging requirements. Packaging requirements are maintained by the Inventory Control Point's packaging activity within the Military Department or Defense Agency, or within the Military Department's System Command. Packaging data retrieval is available from the managing Military Department's or Defense Agency's automated packaging files, CD-ROM products, or by contacting the responsible packaging activity.

6. NOTES

6.1 Intended use. Devices conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. This drawing is intended exclusively to prevent the proliferation of duplicate specifications, drawings, and stock number listings.

6.2 Ordering data. The contract or purchase order should specify the following:

- a. Complete PIN (see 1.2).
- b. Requirements for delivery of one copy of the conformance inspection data or certificate of compliance that parts have passed conformance inspection with each shipment of parts by the manufacturer.
- c. Requirements for packaging and packing.

6.3 Replaceability. Devices covered by this drawing may be used as a substitute for MIL-S-19500/322.

DSCC drawing PIN	Military part number	Commercial part number
01037-1N23WE 01037-1N23WEM 01037-1N23WEMR 01037-1N23WG 01037-1N23WGM 01037-1N23WGMR	JAN1N23WE JAN1N23WEM JAN1N23WEMR JAN1N23WG JAN1N23WGM JAN1N23WGMR	UXAN1N23WE UXAN1N23WEM UXAN1N23WEMR UXAN1N23WG UXAN1N23WGM UXAN1N23WGMR

6.4 Comments. Comments on this drawing should be directed to contact Defense Supply Center, Columbus, ATTN: DSCC-VAC, Post Office Box 3990, Columbus, OH 43216-5000.

6.5 Suggested sources of supply. Suggested sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have concurred with this drawing and have submitted a certificate of compliance (see 3.8 herein) to DSCC-VAC.

DSCC drawing PIN	Vendor similar designation or type number ^{1/}	Vendor CAGE	Vendor name and address
01037-1N23WE 01037-1N23WEM 01037-1N23WEMR 01037-1N23WG 01037-1N23WGM 01037-1N23WGMR	UXAN1N23WE UXAN1N23WEM UXAN1N23WEMR UXAN1N23WG UXAN1N23WGM UXAN1N23WGMR	0EFF4	Micrometrics, Inc. 136 Harvey Road Building B Londonderry NH 03053

^{1/} CAUTION: Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

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